



Material Content Data Sheet



Sales Product Name		BGT 24AT2 E6433		Issued		22. January 2018		
MA#		MA001683770						
Package		PG-VQFN-32-9		Weight*		55.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.375	4.27	4.27	42713	42713
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		146	
	non noble metal	zinc	7440-66-6	0.032	0.06		582	
	non noble metal	iron	7439-89-6	0.647	1.16		11641	
wire	non noble metal	copper	7440-50-8	26.284	47.27	48.50	472684	485053
	noble metal	gold	7440-57-5	0.355	0.64	0.64	6380	6380
	encapsulation	organic material	carbon black	1333-86-4	0.070	0.13		1252
encapsulation	plastics	epoxy resin	-	2.948	5.30		53012	
	inorganic material	silicondioxide	60676-86-0	20.194	36.32	41.75	363156	417420
leadfinish	non noble metal	tin	7440-31-5	1.435	2.58	2.58	25810	25810
plating	noble metal	silver	7440-22-4	0.555	1.00	1.00	9981	9981
glue	plastics	epoxy resin	-	0.162	0.29		2908	
	noble metal	silver	7440-22-4	0.541	0.97	1.26	9735	12643
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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